

Zener Diode DZ2S82000L

DZ2S82000L Silicon epitaxial planar type

For ESD protection

- Features
- High ESD
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: WG

## Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

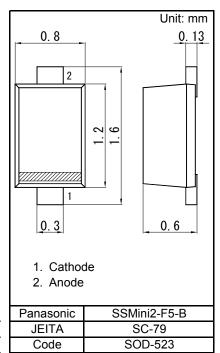
■ Absolute Maximum Ratings Ta = 25 °C

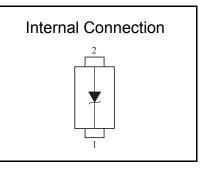
Parameter	Symbol	Rating	Unit	
Total power dissipation <sup>*1</sup>	PT	150	mW	
Electrostatic discharge *2	ESD	±8	kV	
Junction temperature	Tj	150	°C	
Operating ambient temperature	Topr	-40 to +85	°C	
Storage temperature	Tstg	-55 to +150	°C	

 
 Note)
 \*1
 Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm) Soldering size : 0.8 x 0.6 mm

\*2 Test method:IEC61000\_4\_2

( C = 150 pF , R = 330  $\Omega$  , Contact and Air discharge : 10 times )





## ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *1, *2	VZ	IZ = 2 mA	77.0	82.0	87.0	V
Reverse current	IR	VR = 63 V			0.05	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		13		pF
Temperature coefficient of zener voltage *3	SZ	IZ = 2 mA		55.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

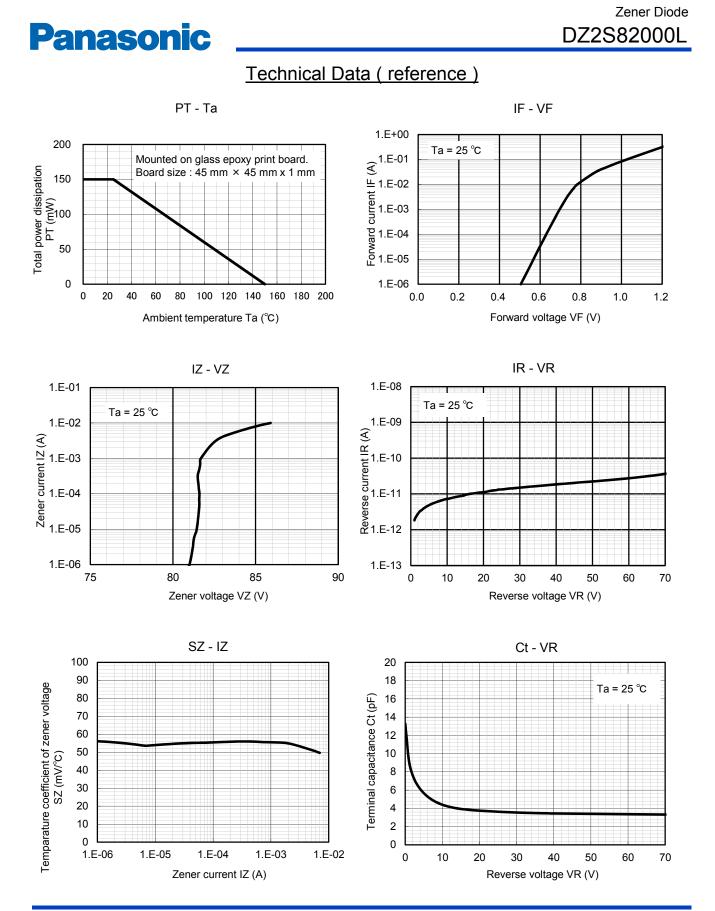
2. Absolute frequency of input and output is 5 MHz.

3. \*1 The temperature must be controlled 25 °C for VZ mesurement.

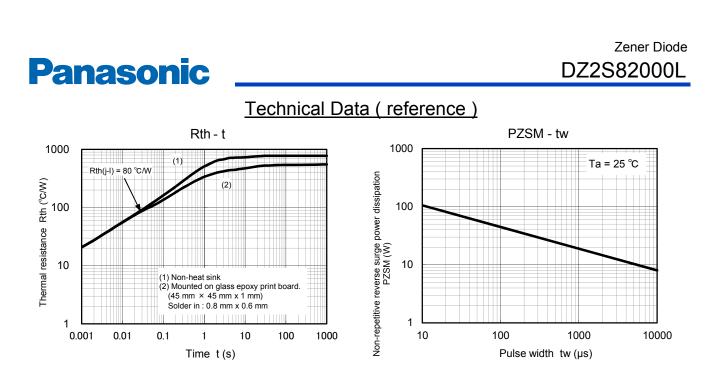
VZ value measured at other temperature must be adjusted to VZ ( 25 °C )

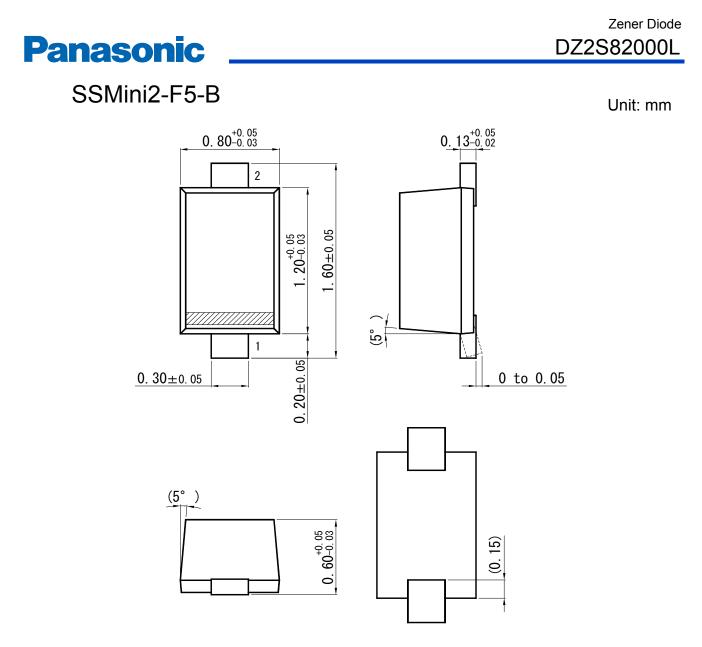
\*2 VZ guaranteed 20 ms after current flow.

\*3 Tj = 25 °C to 150 °C

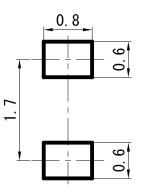


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Land Pattern (Reference) (Unit: mm)



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